

Abstract of the Disclosure:

A leadframe, a housing, a radiation-emitting component formed therefrom, and a method for producing the component includes the leadframe having a mount part with at least one bonding
5 wire connecting area and at least one electrical solder connecting strip into which a separately manufactured thermal connecting part, which has a chip mounting area, is linked. To form a housing, the leadframe is sheathed, preferably, with a molding compound, with the thermal connecting part being
10 embedded such that it can be thermally connected from the outside.

GLM/nt